

L Number	Hits	Search Text	DB	Time stamp
1	956	grinding near4 sanding	USPAT; US-PGPUB	2004/04/22 11:21
2	2112	(strandboard or waferboard or chipboard or fiberboard or particleboard or osb or ((strand or particle or wafer or fiber or chip or wafer) adj1 board)).ti,ab.	USPAT; US-PGPUB	2004/04/22 11:05
3	3	(grinding near4 sanding) and ((strandboard or waferboard or chipboard or fiberboard or particleboard or osb or ((strand or particle or wafer or fiber or chip or wafer) adj1 board)).ti,ab.)	USPAT; US-PGPUB	2004/04/22 11:04
4	8	(strandboard or waferboard or chipboard or fiberboard or particleboard or osb or ((strand or particle or wafer or fiber or chip or wafer) adj1 board)) same (grinding near4 sanding)	USPAT; US-PGPUB	2004/04/22 11:07
5	7	((strandboard or waferboard or chipboard or fiberboard or particleboard or osb or ((strand or particle or wafer or fiber or chip or wafer) adj1 board)) same (grinding near4 sanding)) not ((grinding near4 sanding) and ((strandboard or waferboard or chipboard or fiberboard or particleboard or osb or ((strand or particle or wafer or fiber or chip or wafer) adj1 board)).ti,ab.))	USPAT; US-PGPUB	2004/04/22 11:07
6	14	thickness with (grinding near4 sanding)	USPAT; US-PGPUB	2004/04/22 11:09
7	2	(strandboard or waferboard or chipboard or fiberboard or particleboard or osb or ((strand or particle or wafer or fiber or chip or wafer) adj1 board)) and (thickness with (grinding near4 sanding))	USPAT; US-PGPUB	2004/04/22 11:07
8	14	thickness with (grinding near4 sanding)	USPAT; US-PGPUB	2004/04/22 11:10
9	51	(wood or wooden or woody) with (grinding near4 sanding)	USPAT; US-PGPUB	2004/04/22 11:11
10	293	grinding near4 sanding	EPO; JPO; DERWENT	2004/04/22 11:21
11	4	thickness with (grinding near4 sanding)	EPO; JPO; DERWENT	2004/04/22 11:19
12	31	(wood or wooden or \$7board) with (grinding near4 sanding)	EPO; JPO; DERWENT	2004/04/22 11:23